

Modular Electronics: Present and Future in the LHC experiments

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Outline

- Modular electronics in the current systems
- What has been good with VME or “VME-like” systems
- Possible replacement options
- On-going work in the LHC experiments

Modular electronics in the current systems

- Modular electronics in
 - The trigger systems
 - The TTC and control systems
 - Some of the the readout systems
- Mainly VME or “VME-like”
 - ALICE 69 crates
 - ATLAS 219 crates
 - CMS 194 crates
 - LHCb 146 crates (including the TELL1 crates)
 - **Total** **628 crates**
- CMS uses also CompactPCI at one stage
 - Easy interface to PCs

Use in the trigger systems

- Mainly VME 9U version used
 - Number of I/Os
 - Boundaries between boards to be avoided
- Standard mechanics and power supplies but adhoc backplanes
 - Interconnections between boards

Use in the readout systems

- At the exception of (a part of) ALICE, there is an intermediate stage between the front-end and the DAQ
 - ROD in ATLAS, FED in CMS, TELL1 in LHCb, Router for the ALICE Pixel
- Main functionalities
 - Gathering several low speed FE links
 - E.g. more than 8000 40-Mbps links for the ATLAS SCT
 - Implementing analogue to digital conversion
 - E.g. analogue readout of the CMS tracker
 - Data compression and fast processing
 - E.g. energy, timing and quality factor calculation for calorimeters
 - Data compression and formatting in the TELL1

Use in the readout systems (cont)

- The VMEbus does not see the main dataflow
 - Even no VMEbus in the LHCb TELL1 crates
 - Main dataflow through point to point links to upper stages
 - S-Link or S-Link64 in ATLAS and CMS
 - GbE in LHCb
- VMEbus used for control and monitoring
 - Dedicated common software in ATLAS and CMS
 - ROD Crate DAQ and XDAQ
 - Credit Card PC in the LHCb TELL1
- Additional backplanes for TTC distribution and/or dedicated functionalities where needed

What has been good and less good with VME

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Mechanics and Power Supplies

- Reasonable mechanical design
 - 6U, 9U and mixed
- Reliable power supplies and easy integration in the bin
 - Capability to insert and remove PS without tools
 - 2% failure rate in 2012
- Easiness of adhoc backplanes installation
- Rear transition modules (RTM) of all sorts
 - Heavily used
- Availability of a CERN purchase and maintenance contract
- Too many options for the power supplies
 - 5 V, 3.3 V, ± 12 V, 48 V with different power capabilities

What has been good and less good with VME

VMEbus and Interfaces

- VMEbus is very well known in the community
 - About 30 years of experience
- Simple interface implementation
- Availability of Single Board Computers or performing interfaces
 - ATLAS and ALICE using a family of SBC from Concurrent Technologies
 - CMS using a CAEN interface and a PC
 - In both case easy evolution
- Capability of providing standard common DAQ Ecumenical Workshop
- software
 - ROD Crate DAQ and XDAQ
 - VME libraries
- Relatively cheap despite a high-end crate
 - 640 ChF per slot for a 9U system & 470 ChF per slot for a 6U system
 - Including bin, fan-tray, power supply and SBC
- Parallel bus requiring a lot of connector space and a lot of components
- A bit of an overkill for control applications

Modular electronics for the upgrades

- Is there still a need?
 - Certainly for the trigger
 - Readout might be different from today
 - All front-end digital
 - Use of GBT in a lot of places
 - → more standardisation possible
- Could VME do the job?
 - Bandwidth is not an issue
 - Main data flow not through the crate backplane
 - Level-1 has special requirements
 - VME is already an old standard and we have to consider a system lasting until 2030 – 2040
- Off-detector readout electronics mainly based on FPGAs and will rely on high density of high speed links
 - Large power needed per board (VME 9U limited to less than 100 W)
 - Large space between boards to accommodate heat sinks
 - 3.3 V and 5 V power supplies not adapted

→ ***Useful to consider a replacement***

What could be a replacement to VME?

- VXS as a natural successor of VME
- ATCA or μ TCA
- Direct readout in PCs
 - For readout part only
- No standard
 - Define a bin with Fan Trays and power supplies
 - (GB)Ethernet interfaces on each board
 - Ethernet switches and PCs
 - i.e. a poor man xTCA...
- Next slides on what is going on in the community
- Details about the different standards can be obtained in a presentation by Markus Joos in <https://indico.cern.ch/conferenceDisplay.py?confId=196590>

On-going activities

- ALICE
 - Readout upgrade expected at LS2
 - Upgraded version of the DDL for the DAQ
 - No specific development yet for modular electronics located before
- ATLAS
 - Short term upgrades (CSC RODs, Topological Trigger, FTK) as well as upgrades for LS2 using ATCA
 - Willing to be compatible with upgrades to be done during LS3
- CMS
 - New FEDs (Pixels, HCAL, end-cap GEMs) and upgraded trigger using μ TCA
 - No decision concerning LS3
- LHCb
 - Upgrade for LS2 using ATCA (Tell11 \rightarrow Tell40)

xTCA is clearly the replacement option...

ATCA in a nutshell

- Advanced Telecommunications Computing Architecture
- 8U board size (called blade)
- Up to 16 boards (blades) per crate (called shelf)
- Up to 400 W per board
- 48 V power line distributed to boards
 - Local point of load DC-DC converters on the board
- Up to 200 differential lines per blade
 - Full mesh or dual star
 - Up to 40 Gbps per channel
 - Agnostic
 - Base Interface and Fabric Interface
- Complete (and complex) management of the boards based on Intelligent Platform Management Interface (IPMI)
 - 1 or 2 shelf managers per shelf
- Three connector zones
 - Power, Data Transfer, User defined
- Rear Transition Modules (RTM) capability

ATCA components

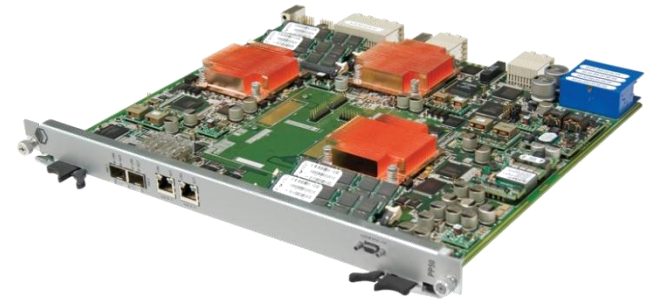
Shelves



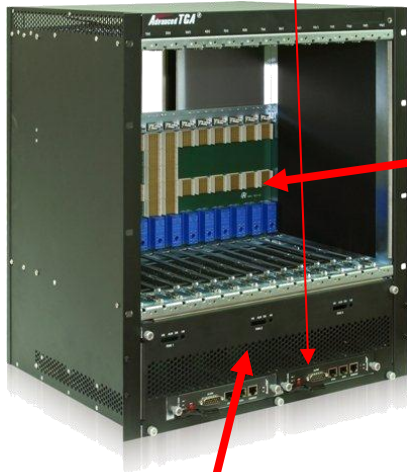
Shelf manager(s)



Switch blade



Payload card



Backplane



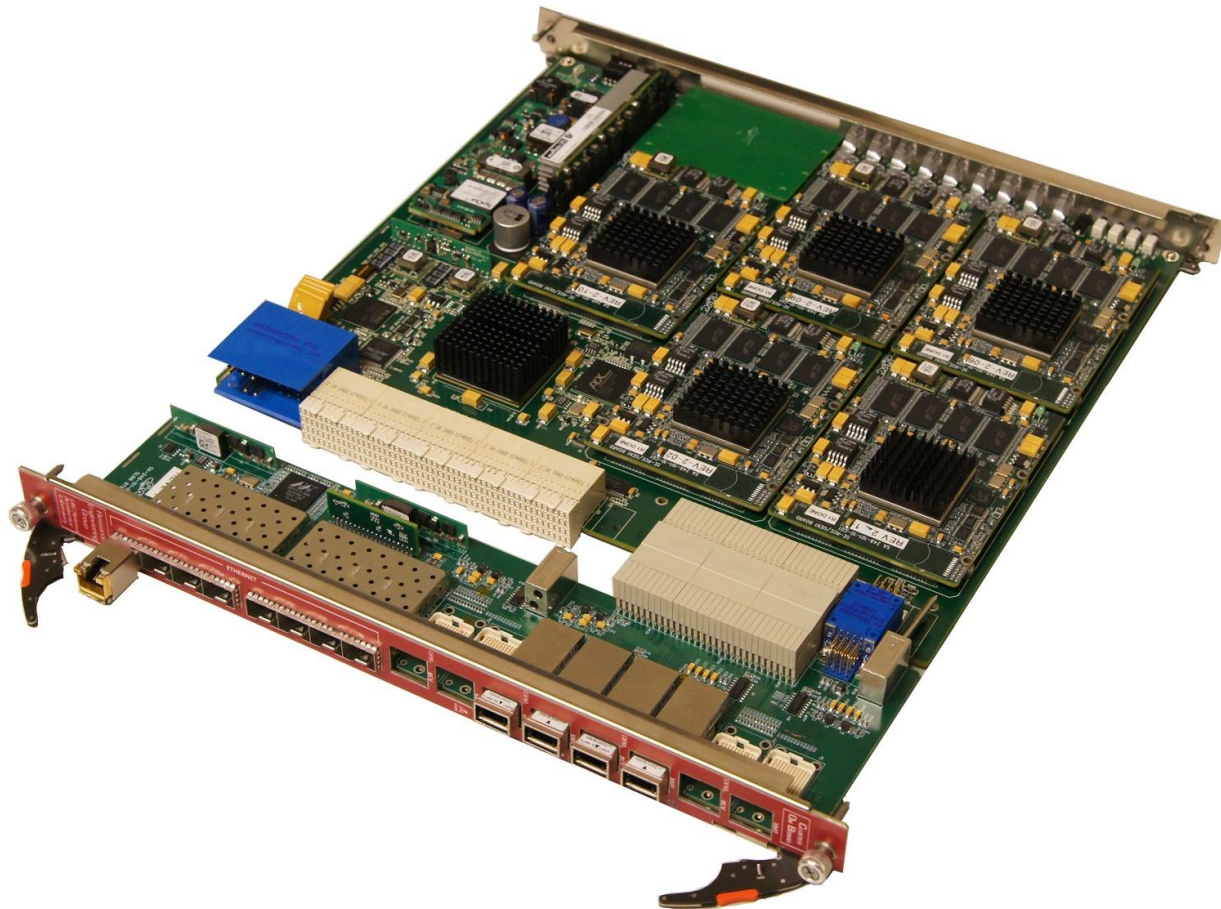
AMC carrier



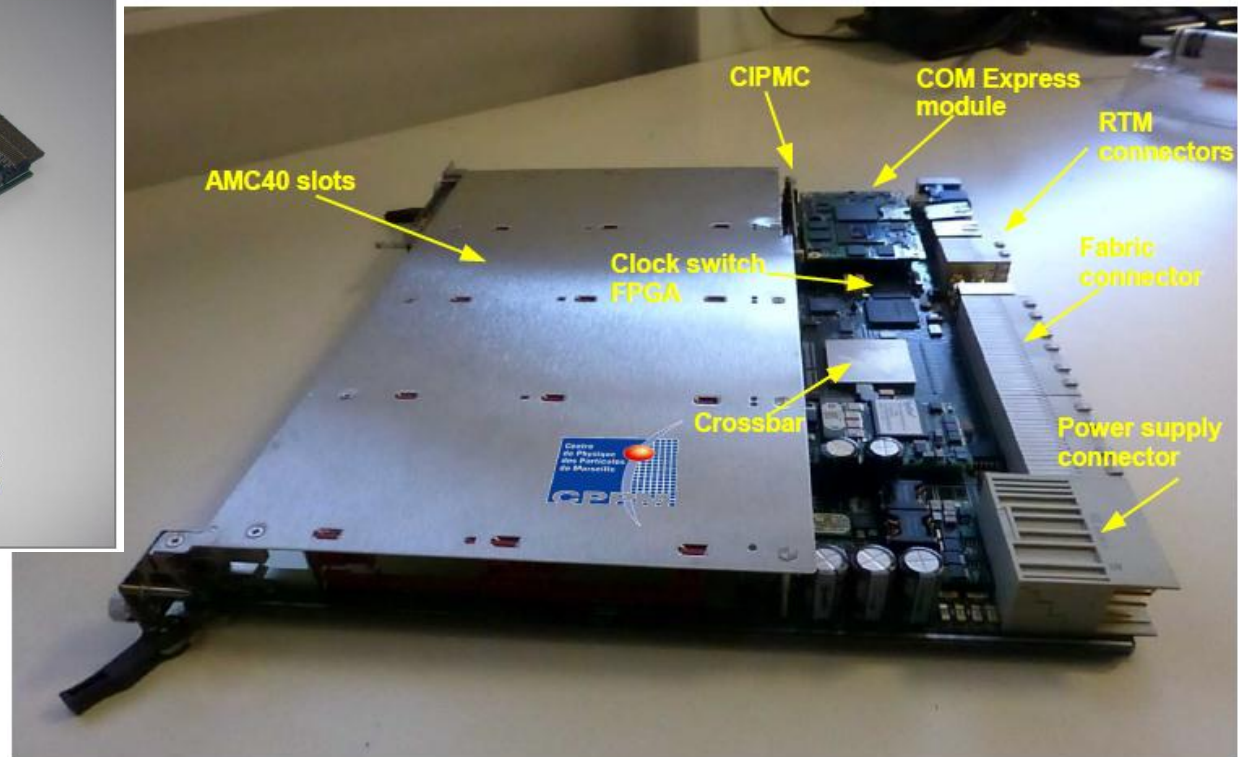
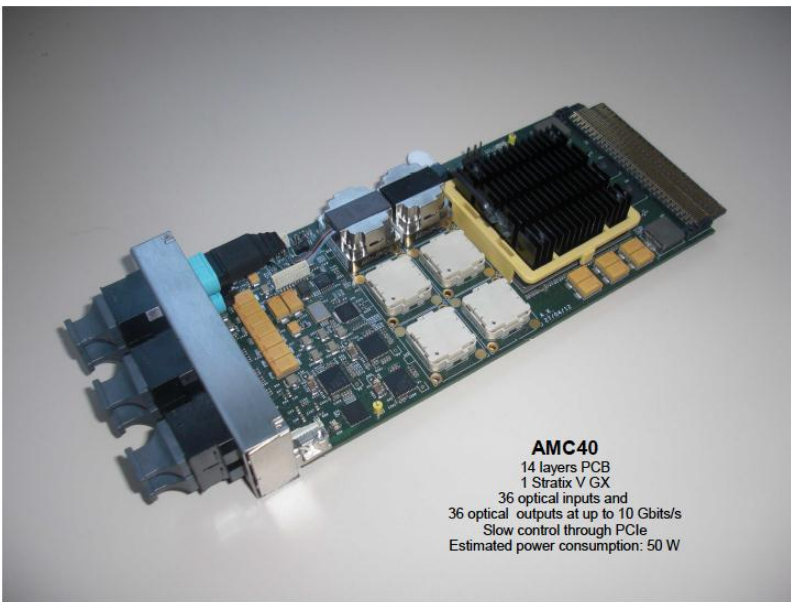
Rear Transition Module

Hot-swap fans

SLAC blade



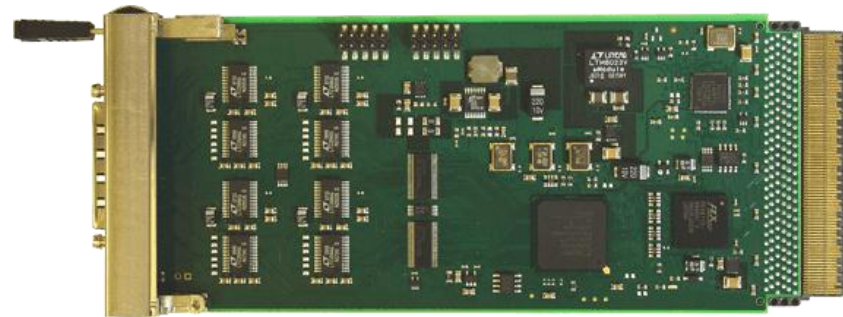
LHCb TELL40



Advanced Mezzanine Cards (AMC)

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- Mezzanine cards for ATCA blades to modularize if needed
- 6 form factors
 - 2 widths, 2 heights and 1 depth
- 80 W max – 12 V supply
- 40 LVDS pairs for connectivity
 - Ethernet, PCIe, RapidIO, ...
- Basis for μ TCA

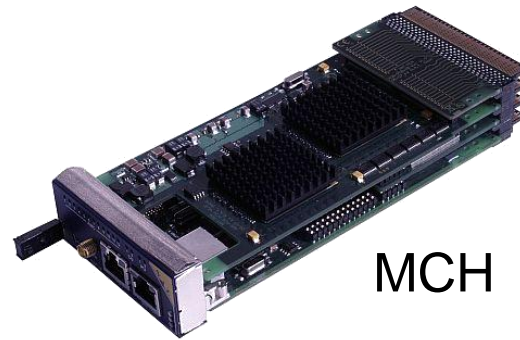


μTCA in a nutshell

- Try and make a smaller and cheaper (?) system than ATCA and put AMCs directly in a shelf
- Connectivity:
 - 4 AMC LVDS pairs defined as “Common Options” (2 Eth. & 2 SAS ports) and connect to 1 or 2 MCH boards which provide the switching
 - 8 AMC LVDS pairs defined as (extended) fat pipes (1 or 10 G Eth, PCIe, RapidI/O). Connection to MCH not fully standardized
 - Remaining 8 LVDS pairs not defined (can be used e.g. for direct connection to neighboring module or as a timing distribution bus)
- System management based on IPMI / I2C
- MTCA.4 adds RTMs and other features (μTCA for physics)
- Hot-swap support for AMC, MCH, PSU & cooling
- High degree of freedom
 - Height (13, 18 & 28 mm) and width (74 & 149 mm)
 - Communication protocol
 - Backplane routing



μTCA Components



MCH

Courtesy Markus Joss



Shelves

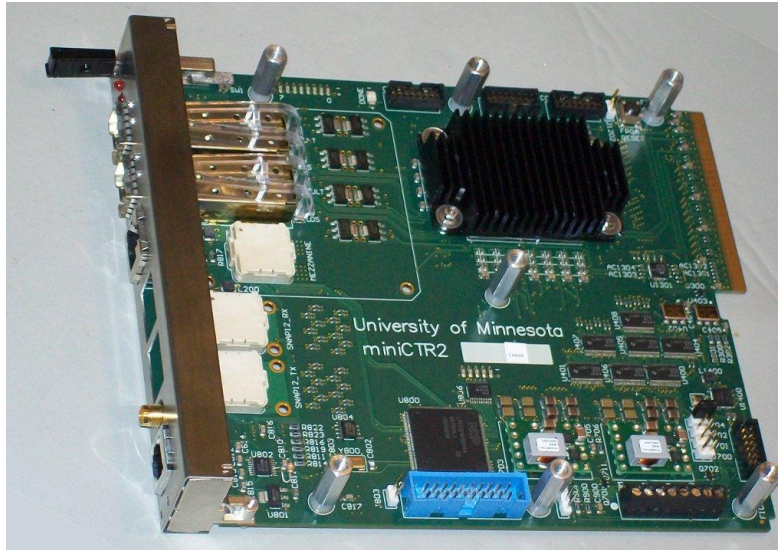


AMCs

CMS Developments

SFP Optical Transceivers

SNAP12
Optical arrays

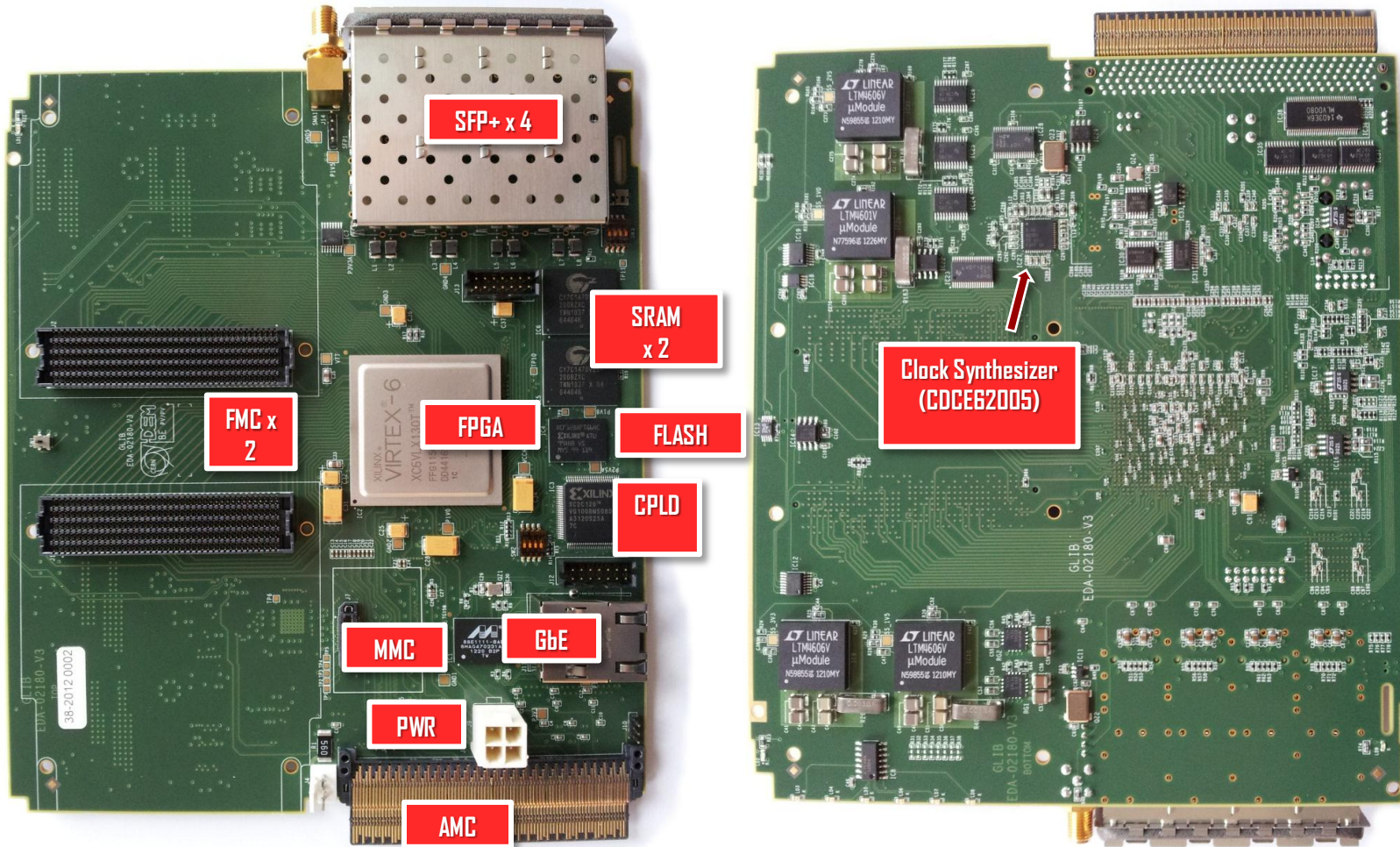


For HCAL upgrade

For trigger upgrade
72 x 10 Gb bidirectional optical links



GLIB



What do we want/need?

- Hardware
 - Decide on a standard with a limited number of variants
 - Get the same kind of procurement and maintenance contracts as we have for VME
 - As common as possible basic bricks and components
- Software
 - Provide the same kind of infrastructure as today
 - E.g. XDAQ and ROD Crate DAQ for ATLAS and CMS
 - Be able to control and monitor the hardware (power supplies, cooling, temperatures,...) in DCS

What's going on?

- CMS has selected μ CTA and they plan procurement of crates relatively soon
- LHCb has selected ATCA for their TELL40 (see later)
 - Installation during LS2
- ATLAS is (slowly) defining a minimum set of requirements
 - Power, preferred protocol for the fabric and the base interface, TTC distribution, cooling, backplane topology (full mesh preferred)
 - Start looking at integration in DCS and ways of implementing the ROD crate DAQ (see later)
 - Discussion with LHCb to have commonalities
 - During LS1 very few systems to be installed. More during LS2. No large deployment before LS3

Crates Procurement

- The CERN ESE team taking care of the VME crates is starting looking at ATCA and μ TCA systems in view of putting in place procurement and maintenance contracts
 - Investigating interoperability issues
 - Developing some “tools” for future H/W evaluations
 - That will take a bit of time (~2 years)
- It is very likely that ATLAS and LHCb will agree on a common ATCA crate
 - Based on highest demand
 - E.g. Full Mesh backplane
- There might be a schedule problem with the procurement of the CMS μ TCA crates
- Some equipment will be made available in the electronics pool
- Available tool for checking interoperability of xTCA devices

Integration in existing systems

- Nice piece of hardware which requires “a bit” of software and xTCA is not the simplest system we can think of...
- It needs to be integrated in
 - DCS
 - In the DAQ framework (e.g. XDAQ and ROD Crate DAQ for CMS and ATLAS)

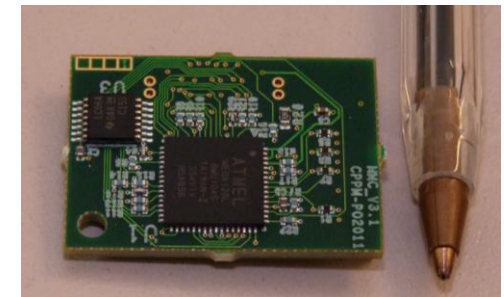
Integration in DCS

- IPMI is a very powerful tool
- IPMC and MMC needed
 - Two common developments available
 - To be used by all
- Software tools
 - LHCb: ipmitool -> DIM -> DCS (WIN-CC)
 - ATLAS: ipmitool -> (open) HPI -> SNMP -> PVSS (WIN-CC-OA)
 - For “basic” control



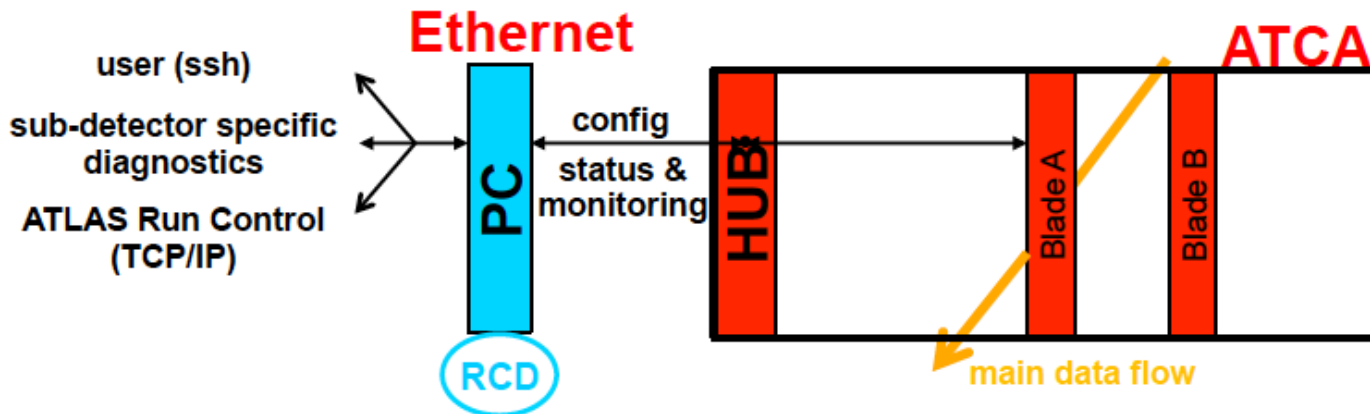
IPMC (LAPP)

MMC (DESY/CPPM/CERN)



ROD Crate DAQ

→ use a PC and a protocol over Ethernet for hardware access:

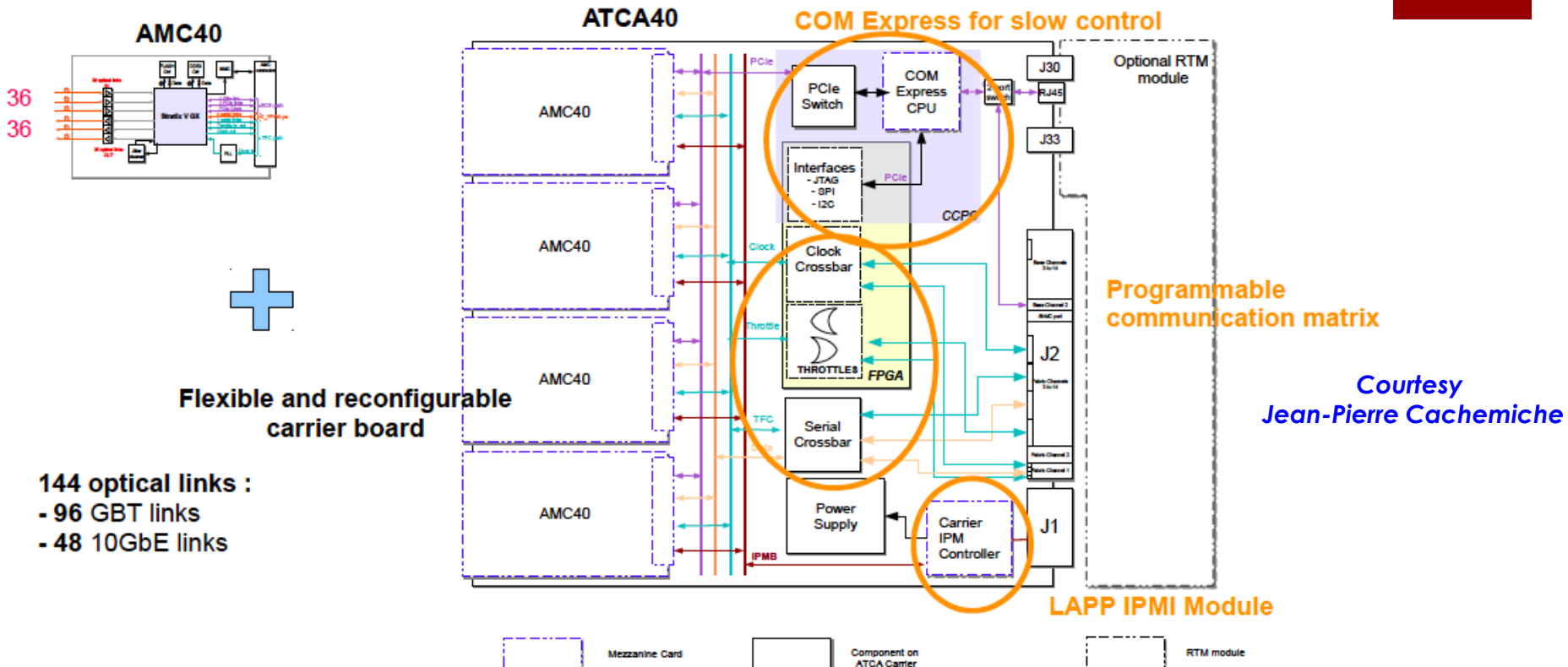


Courtesy Ralf Spiwoks

- PC runs ROD Crate DAQ controller
- PC communicates with blades using Ethernet via a hub. IP (UDP?) packets routed over hub in ATCA crate to each blade (base or fabric).
- Requires a protocol on top of UDP/IP in order to provide hardware-specific transactions (READ/WRITE), e.g. like **IPBus**
- Features:
 - mapping of addresses very similar to VMEbus
 - requires UDP/IP stack in the firmware

Developed by CMS. Based on UDP. Simple way to access registers etc.

LHCb TELL40



Only firmware and datapath programming change
to implement readout, time distribution, slow control or trigger interface

- Can really be of interest for a lot of applications

Summary (1)

- There is still a need for modular electronics in the future
- VME has been very successful but is not really adapted to future needs
- All the developments are in xTCA
 - Good mechanics, good cooling, powerful control
 - High complexity
 - Easy to get incompatible profiles
- Aim at having the same kind of support as we had for VME
 - Will require a bit of time
- Common effort on some parts (hardware and software) already started
 - IPbus, IPMC, MMC, IPMItool, ...

Summary (2)

- We are not alone
 - ITER, DESY, ...
- xTCA Interest Group (Markus Joos)
 - Next meeting in April at CERN
 - xTCA IG web site twiki.cern.ch/twiki/bin/view/XTCA/WebHome
 - Mailing list xtca-news@cern.ch
- We can share common designs much more than in the past

Thanks to all those I bothered with stupid questions and to whom I requested nice pictures which I have not been able to present